

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology
- ★ 100% EAS Guaranteed

## Product Summary

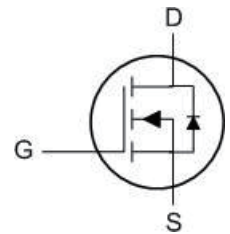
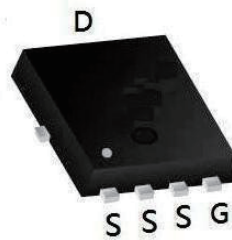
BVDSS	RDSON	ID
30V	5.0mΩ	62A

## Description

The S60N03D is the high cell density trench N-ch MOSFETs, which provide excellent RDSON and gate charge for DC/DC converters application.

The S60N03D meet the RoHS and Green Product, requirement 100% EAS guaranteed with full function reliability approved.

## PDFN3\*3 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D@Tc=25°C</sub>	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	62	A
I <sub>D@Tc=100°C</sub>	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	38	A
I <sub>D@TA=25°C</sub>	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	27	A
I <sub>D@TA=70°C</sub>	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	24	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	135	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	29.8	mJ
I <sub>AS</sub>	Avalanche Current	27	A
P <sub>D@Tc=25°C</sub>	Total Power Dissipation <sup>4</sup>	30	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	50	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	4.6	°C/W

**Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise specified)**

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Units
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=20A$	---	5	6.3	m $\Omega$
		$V_{GS}=4.5V, I_D=15A$	---	6.9	9	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	---	2.5	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=24V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	uA
		$V_{DS}=24V, V_{GS}=0V, T_J=55^\circ\text{C}$	---	---	5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=5V, I_D=20A$	---	67	---	S
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	1.7	---	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{DS}=15V, V_{GS}=4.5V, I_D=15A$	---	8	---	nC
$Q_{gs}$	Gate-Source Charge		---	2.4	---	
$Q_{gd}$	Gate-Drain Charge		---	3.2	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=15V, V_{GS}=10V, R_G=3.3\Omega, I_D=15A$	---	7.1	---	ns
$T_r$	Rise Time		---	40	---	
$T_{d(off)}$	Turn-Off Delay Time		---	15	---	
$T_f$	Fall Time		---	6	---	
$C_{iss}$	Input Capacitance		---	814	---	pF
$C_{oss}$	Output Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$	---	498	---	
$C_{rss}$	Reverse Transfer Capacitance		---	41	---	

**Diode Characteristics**

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Units
$I_S$	Continuous Source Current <sup>1,6</sup>	$V_G=V_D=0V$ , Force Current	---	---	60	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V
$t_{rr}$	Reverse Recovery Time	$I_F=20A, di/dt=100A/\mu s$ ,	---	15	---	nS
$Q_{rr}$	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	25	---	nC

**Note :**

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=24A$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

Typical Performance Characteristics

Figure 1: Output Characteristics

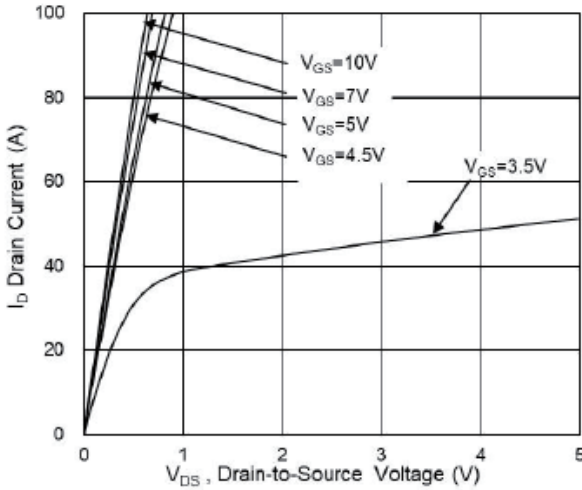


Figure 2: Typical Transfer Characteristics

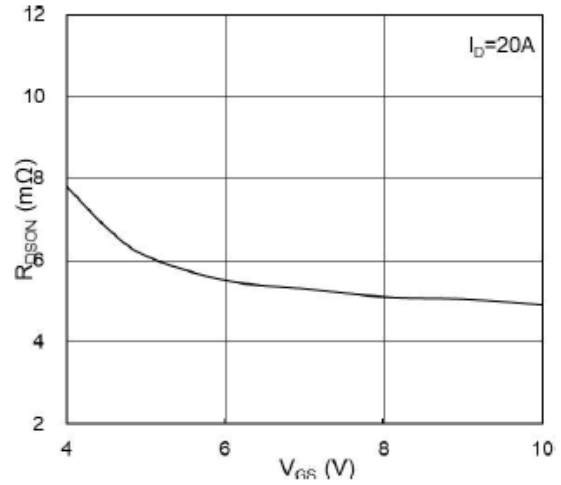


Figure 3: Source Drain Forward Character

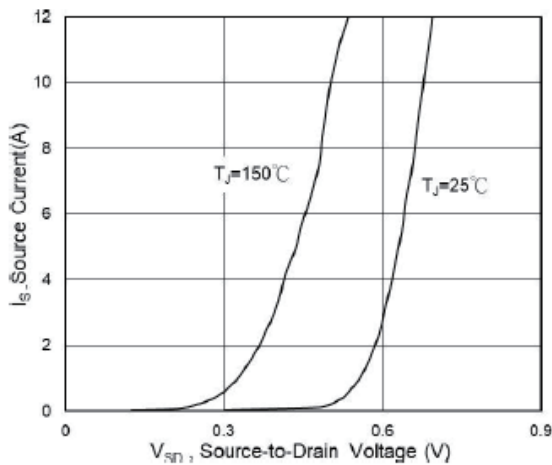


Figure 4: Gate-Charge Characteristics

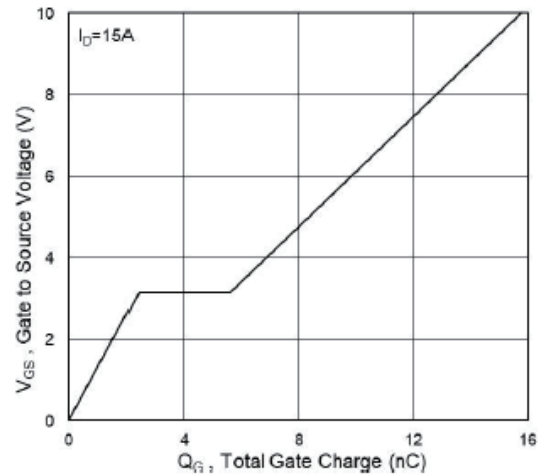


Figure 5: Normalized V\_GS(th) vs T\_J

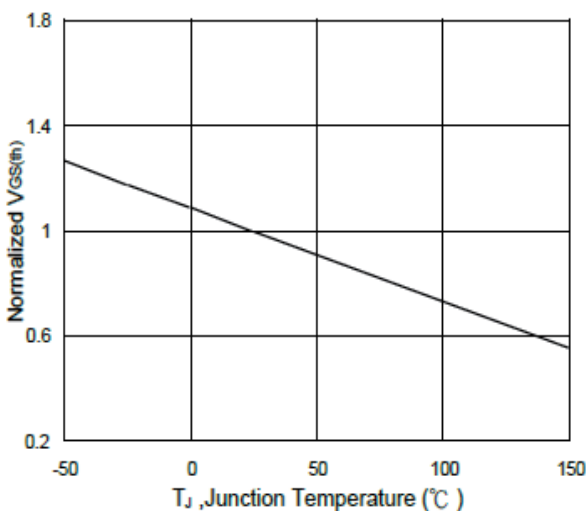
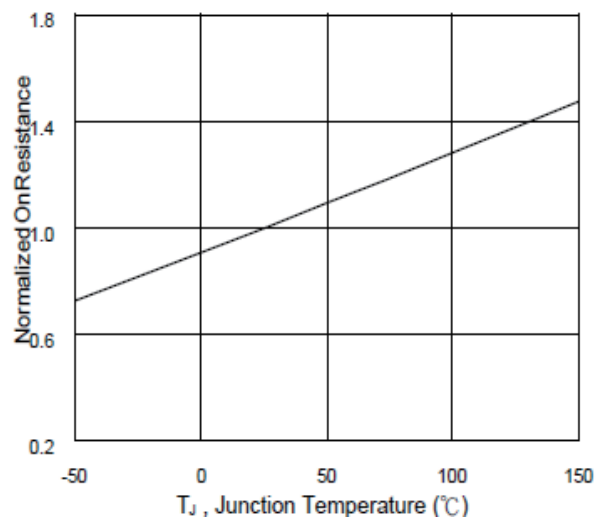


Figure 6: Normalized R\_DS(on) vs T\_J



Typical Performance Characteristics

Figure 7: Capacitance

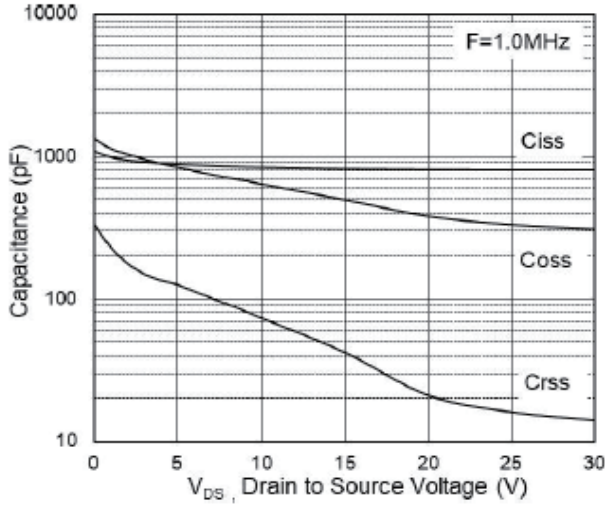


Figure 8: Safe Operating Area

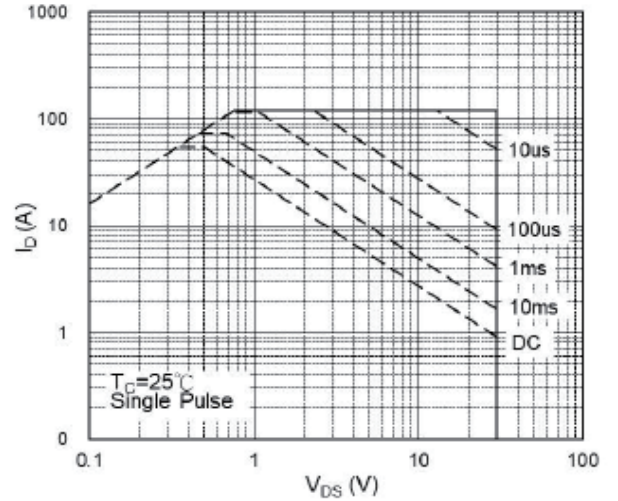


Figure 9: Normalized Maximum Transient Thermal Response

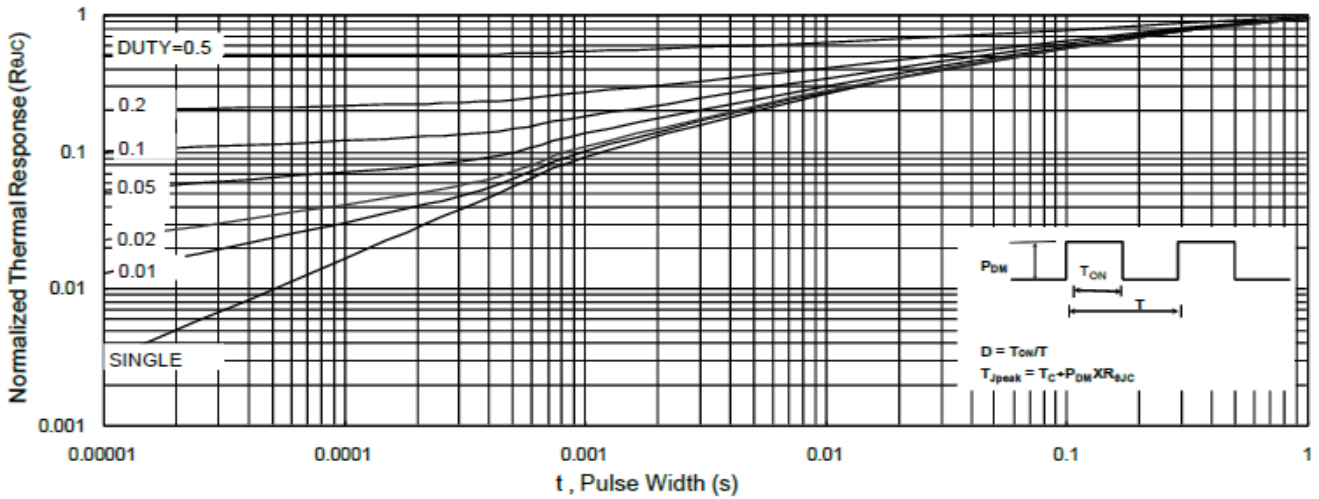


Figure 11: Switching Time Waveform

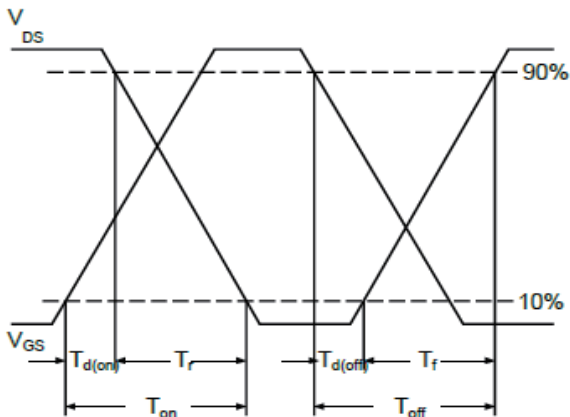
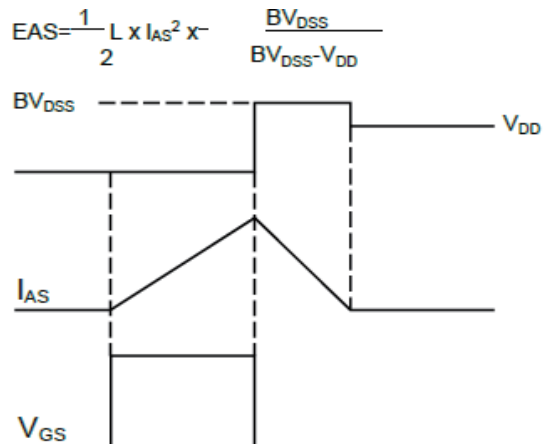
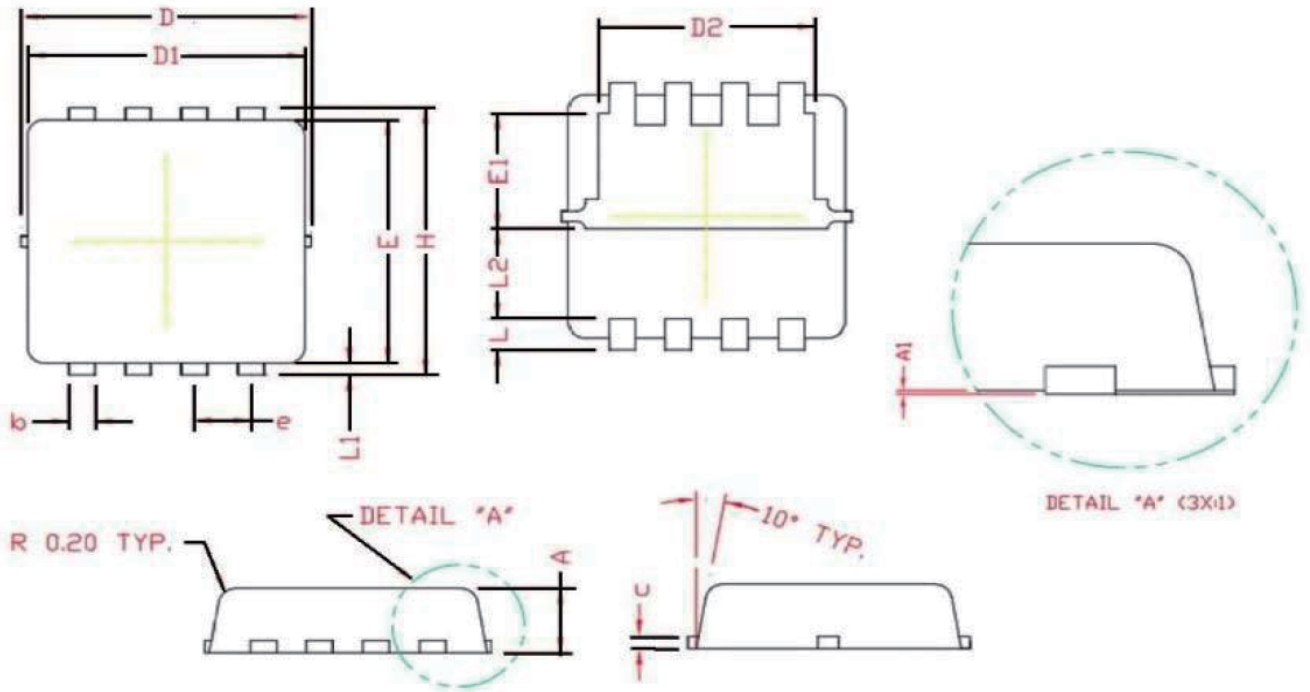


Figure 10: Unclamped Inductive Switching



PDFN3\*3-8L Package Information



Symbol	MILLMETER		
	MIN	MON	MAX
A	0.70	0.80	0.90
A1	0.00	0.03	0.05
b	0.24	0.30	0.35
c	0.10	0.15	0.20
D	3.25	3.32	3.40
D1	3.05	3.15	3.25
D2	2.40	2.50	2.60
E	3.00	3.10	3.20
E1	1.35	1.45	1.55
e	0.65BSC.		
H	3.20	3.30	3.40
L	0.30	0.40	0.50
L1	0.10	0.15	0.20
L2	1.13REF.		